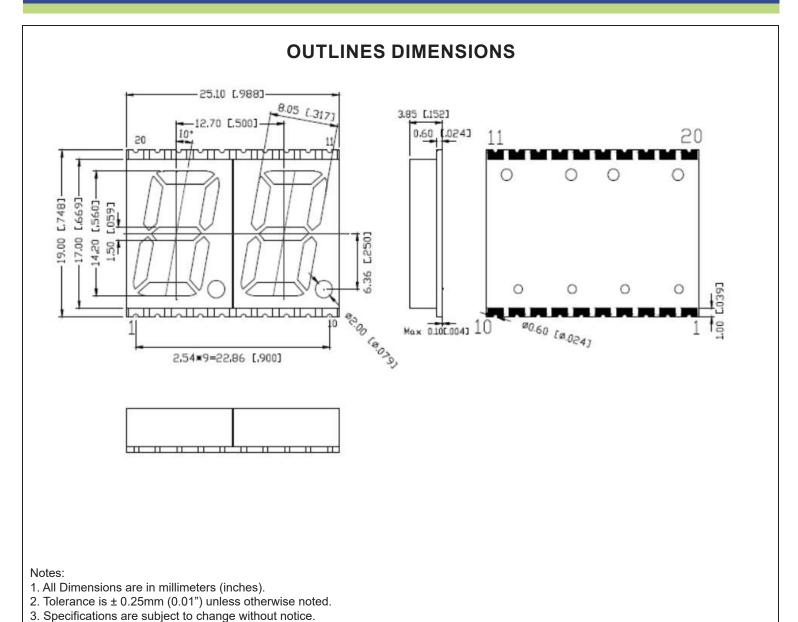


SPECIFICATIONS SDDA56W2W



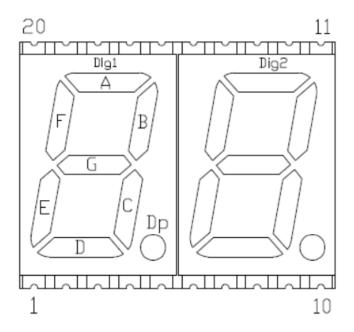
Part Number	Chip Material	Color of Emission Lens Type		Description	
SDDA56W2W	InGaN	White	White Segment	Common Anode	

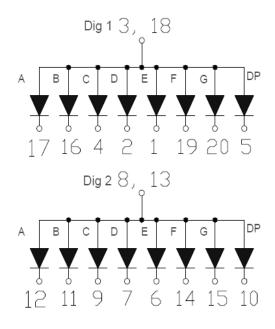


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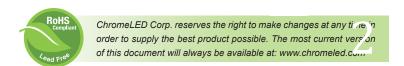


TYPICAL INTERNAL EQUIVALENT CIRCUIT





Common Anode





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit				
Power Dissipation	Pb	114	mW				
Pulse Forward Current	lFP	100	mA				
Continuous Forward Current	lF	30	mA				
Reverse Voltage Segment	VR	5	V				
Operating Temperature Range	Topr	-40~+105	°C				
Storage Temperature Range	Тѕтс	-40~+105	°C				

IFP = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Deremeter	Symbol	Test Condition	Value			Linit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	I _F = 10mA	-	60	-	mcd
Forward Voltage	VF	I⊧ = 20mA	-	3.2	3.8	V
Reverse Leakage Current	lR	V _R = 5V	-	-	10	μΑ
	X	I _F = 20mA	1	0.27	-	-
Chromaticity Coordinates	Υ	I _F = 20mA	-	0.25	-	-



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OPTICAL CHARACTERISTIC CURVES

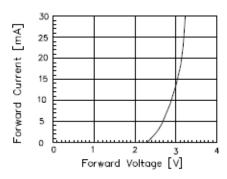


Fig 1. Forward Current vs. Forward Voltage

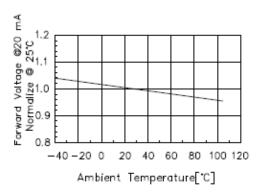


Fig 3. Forward Voltage vs. Temperature

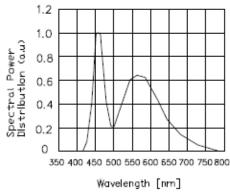


Fig 5. Spectral Power Distribution vs. Wavelength

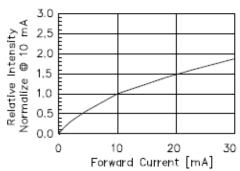


Fig 2. Relative Intensity vs. Forward Current

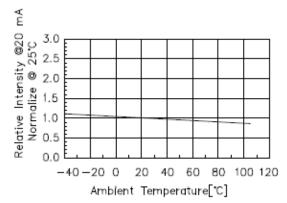


Fig 4. Relative Intensity vs. Temperature

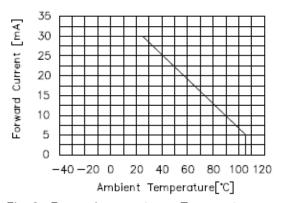


Fig 6. Forward current vs. Temperature

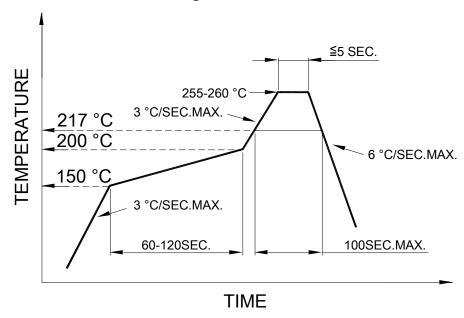


SOLDERING CONDITIONS - DISPLAY TYPE LED

SMT REFLOW SOLDERING INSTRUCTIONS

SMT Soldering Profile

Pb free reflow soldering Profile



- We recommend the reflow temperature 245°C (+/- 5°C).
 The maximum soldering temperature should be limited to 260°C.
- Number of reflow process shall be 2 times or less.

SOLDERING IRON

Basic spec is ≦4 sec when 260°C. If temperature is higher, time should Be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller Than 15W, and temperature should be controllable. Surface temperature Of the device should be under 230°C.

REWORK

- Customer must finish rework within 3 sec. under 350°C.
- The head of soldering iron cannot touch copper foil.

